



# THE BEST IN CPU HEAT DISSIPATION



LOW VOLATILITY



HIGH THERMAL  
CONDUCTIVITY



SILICON  
POLYMER

## THERMAL COMPOUND

HIGH CONDUCTIVITY THERMAL COMPOUND KIT



### SPECIALLY-ENGINEERED

Our silicon polymer-based highly-engineered compound will fill in any gaps between your processor and your cooling unit to maximize heat transfer and lower operating temperatures.



### NO GAPS

It will fill in any gaps between your processor and your cooling unit to maximize heat transfer and lower operating temperatures.



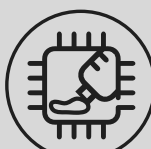
### HIGH CONDUCTIVITY

It's high conductivity range of 13.5 W/m.k will ensure heat is transferred away from your CPU and into your cooling system to be dissipated.



### NO CURING REQUIRED

You read that right, you don't need to add anything or wait for the paste to "set", simply apply and start gaming again.



### EASY APPLICATION

Simply press on the syringe and apply to your CPU, then spread it to an even coat with the included applicator. It will not lose its consistency in storage, and will never dry or crack after application.

## APPLY & START GAMING AGAIN

Whatever you know it as, we assure you that YEYIAN's **Thermally Conductive Compound Kit** will define CPU heat dissipation for you from now on.

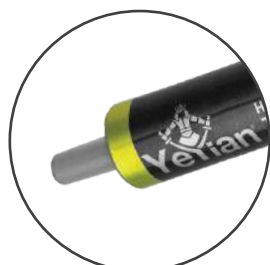
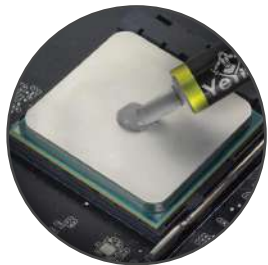
Our new Thermally Conductive Compound is not just easy on your wallet, easy to clean up with any lint-free absorbent paper towel, easy to apply to your CPU and easy to spread evenly with the included applicators, but it also doesn't require you to wait for it to cure!

Our specially-engineered compound is ready to go the moment you finish applying it, and you can safely store it away knowing that the YEYIAN Thermally Conductive Compound won't lose its viscosity.



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## HIGH CONDUCTIVITY THERMAL COMPOUND KIT



### MATERIAL PROPERTIES

Property	Value
Property	YCT-PHTC-01
Color	Gray
Form	One-part; noncuring
Viscosity at Low Strain Rate	1,200 Pa-s
Viscosity at High Strain Rate	100 Pa-s
Specific Gravity	2.6
Volatile Content, 48 hours at 125° C	178°/178°
Thermal Conductivity	13.5W/m-K
Thermal Resistance at 25 N/cm <sup>2</sup>	0.04 C-cm <sup>2</sup> /W
Bond Line Thickness at 25 N/cm <sup>2</sup>	0.02 mm / 0.0008 in
EAN	7503033057162